

**IN THE CLAIMS:**

Claims 4, 7, and 13 have been amended herein. All of the pending claims 1 through 21 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

**Listing of Claims:**

1. (Previously Presented) An automolding system comprising:  
providing a substrate having a surface having a layer of resist on a portion thereof in the automolding system; and  
removing at least a portion of the layer of resist and at least a portion of the contaminants from the substrate using a laser in the automolding system.
2. (Previously Presented) The automolding system of claim 1, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.
3. (Previously Presented) The automolding system of claim 1, further comprising:  
a mold; and  
encapsulating the substrate in the mold in the automolding system.
4. (Currently Amended) A ~~A~~ molding system comprising:  
providing a substrate having a surface having a layer of resist on a portion thereof in the molding system;  
removing at least a portion of the layer of resist and contaminants from the substrate using a laser in the the molding ~~automolding~~ system.
5. (Previously Presented) The molding system of claim 4, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

6. (Previously Presented) The molding system of claim 4, further comprising:  
a mold in the molding system for encapsulating the substrate.

7. (Currently Amended) A system for molding comprising:  
providing a substrate having a surface having a layer of resist on a portion thereof for molding in the system;  
removing at least a portion of the layer of resist and some contaminants from the substrate using a laser in molding ~~the automolding~~ system.

8. (Previously Presented) The system of claim 7, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

9. (Previously Presented) The system of claim 7, further comprising:  
a mold in the system for encapsulating the substrate.

10. (Previously Presented) An automolding system comprising:  
placing a substrate having a surface having a layer of resist on a portion thereof in the automolding system; and  
removing at least a portion of the layer of resist and at least some of the contaminants from the substrate using a laser in the automolding system.

11. (Previously Presented) The automolding system of claim 10, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

12. (Previously Presented) The automolding system of claim 10, further comprising:  
a mold for encapsulating the substrate in the automolding system.

13. (Currently Amended) In a molding system comprising:  
placing a substrate having a surface having a layer of resist on at least a portion thereof in the molding system; and

removing at least a portion of the layer of resist and at least some of the contaminants from the substrate using a laser in the molding automolding system.

14. (Previously Presented) In the molding system of claim 13, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

15. (Previously Presented) In the molding system of claim 13, further comprising: a mold in the molding system for encapsulating the substrate.

16. (Previously Presented) A system for molding comprising:  
placing a substrate having a surface having a layer of resist on at least a portion thereof for molding in the system; and  
removing at least a portion of the layer of resist and at least some of the contaminants from the substrate using a laser in the automolding system.

17. (Previously Presented) The system of claim 16, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

18. (Previously Presented) The system of claim 16, further comprising:  
a mold in the system for encapsulating the substrate.

19. (Previously Presented) An automolding system having a cleaning apparatus comprising:  
introducing a substrate having a surface having a portion thereof covered with a layer of resist in the automolding system; and  
removing at least a portion of the layer of resist and at least some of the contaminants from the substrate using a laser in the automolding system.

20. (Previously Presented) The automolding system of claim 19, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

21. (Previously Presented) The automolding system of claim 19, further comprising:  
a mold for encapsulating the substrate in the automolding system.

22. through 40. (Canceled)